REQUEST FOR INTERVIEW GROUP 2814 PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q58486

Kouki OGAWA, et al.

Appln. No.: 09/538,469

Group Art Unit: 2814

Examiner: Nathan W. Ha Confirmation No.: 6688

Filed: March 29, 2000

(ECHHOLOGY CENTER 2800 CAPACITOR-BUILT-IN TYPE PRINTED WIRING SUBSTRATE, PRINTED

WIRING SUBSTRATE, AND CAPACITOR

REQUEST FOR INTERVIEW

Commissioner for Patents Washington, D.C. 20231

Sir:

For:

Applicants respectfully request an Interview with the Examiner to discuss an issue remaining in this case prior to proceeding with an Appeal. At issue is whether or not U.S. Patent 6,218,729 to Zavrel, Jr. et al. discloses a "capacitor accommodation cavity" as required by the rejected claims.

As noted by the Examiner in the final Office Action dated August 20, 2002 (page 4), a "cavity" is a hollow area within a body. Zavrel does not disclose or illustrate any cavity for accommodating a capacitor or any other component for that matter. To the contrary, Zavrel clearly discloses that passive components including capacitor 804 are fashioned by selectively etching metal interconnect layers, and a capacitor accommodation cavity is <u>not</u> disclosed.

The relevant portions of Zavrel are reproduced at page 5 of the amendment filed July 11, 2002 (copy attached). Fig. 10 of Zavrel illustrates the method of depositing insulating layers and

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metal layers, which includes drawing patterns and etching the metal layers to form the various plates and intervening dielectric of the resulting capacitor. It is respectfully submitted that there is no capacitor accommodation cavity.

Respectfully submitted,

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Date: October 2, 2002

Abraham J. Rosner Registration No. 33,276

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